



# Process Change Notification

PCN Number: PCN-2017-88

PCN Notification Date: 01/16/2018

## Informational PCN: Amended ver. 2.0

ANST Site 24LD TSSOP High Density Lead Frame Change

Dear Customer,

This notification is to advise you of the following ANST Site 24LD TSSOP High Density Lead Frame change(s).

The described change(s) within this PCN will not take effect (i.e. Ship) any earlier than 60 days from this notification. Cirrus Logic has already successfully completed the qualification of this change.

Cirrus Logic would like to take this opportunity to thank our customers for their cooperation and support in this respective matter.

If you have any questions, please contact your Sales Representative.

Sincerely,

Quality Systems Administrator  
Cirrus Logic Corporate Quality  
Phone: +1(512) 851-4000

\* Note: Amended for inclusion of "[R]" in all part numbers to support Tape N Reeled Material.





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## Anticipated Impact on Material Declaration:

- No Impact to the Material Declaration       Material Declarations or Product Content reports are driven from production data and will be available following the production release.

## Product Affected:

Device	Cirrus Logic Part Number
1	CS4270-xZZ[R]/C0
2	CS5351-xZZ[R]/E
3	CS5361-xZZ[R]/E
4	CS5363-DZZ[R]/E
5	CS4349-xZZ[R]/C2
6	CS4350-xZZ[R]/C2
7	CX4350-DZZ[R]/C2
8	CS5381-KZZ[R]/D

## Changes To Product Identification Resulting From This PCN:

The Cirrus Logic component symbolization on the external face of the device reflects the designated Assembly Site.

**There is "NO CHANGE" to the external face of the designated components.**

The Qualification Plans are designed using JEDEC and other applicable industry standards. An overall summary of the Qualification results will be submitted upon completion.

## Qualification

CS5363-DZZ[R]/E, CS4350-DZZ[R]/C2 & CS5381-KZZ[R]/D		Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test	Standard	Conditions	# of Lots	Qty/ Lot	Read Point(s)	Fail Criteria	Results (PASS/FAIL)
<b>WBP</b> (Wire Bond Pull)	MIL-STD-883 Method 2011	Paragraph 3 (Procedure) 30 Bonds	1 lot / Device	5	Pre-Encapsulation	0 fails	Pass
<b>WBS</b> (Wire Bond Shear)	JESD22-B116	Paragraph 4 (Procedure) 30 Bonds	1 lot / Device	5	Pre-Encapsulation	0 fails	Pass
<b>SD</b> (Solderability)	JESD22-B102	93°C / 8 Hr steam age and then 245°C solder bath / 5 seconds before SD	1 lot / Device	15	Solderability	0 fails	Pass
<b>ED</b> (Electrical Distribution)	JESD86A	Parametric limits per datasheet or user spec	1 lot / Device	5	Zero Hours	0 fails	Pass
<b>Pre-Conditioning</b>	JESD22-A113	24 Hr Bake, 192Hr -30°C/ 60%RH Soak, 3x 260°C Peak Reflow	1 lot / Device	200	Pre-Con MSL3	0 fails	Pass
<b>Temperature Cycle</b>	JESD22- A104	Condition C -65°C to +150°C / Air to Air / Post Pre-Condition 500 Cycles	1 lot / Device	80	500 Cycles	0 fails	Pass
<b>Tomography</b>	J-STD_035	C-SAM	1 lot / Device	22, 22, 22	Zero Hrs, Pre-Condition, TC 500 Cycles	0 fails, 0 fails, 0 fails	Pass
<b>uHAST</b>	JESD22-A118	130°C/85%RH Post Precondition	1 lot / Device	80	96 hours	0 fails	Pass
<p><b>Notes:</b> The CS4270-xZZ[R]/C0, CS5351-xZZ[R]/E, CS5361-xZZ[R]/E, CS4349-xZZ[R]/C2 &amp; CX4350-DZZ[R]/C2 material is QBS (Qualified By Similarity).</p> <p><b>Reliability Qualification Results:</b></p> <ul style="list-style-type: none"> <li>Qualification tests “pass” on zero fails for each test</li> </ul>							

